

DRV2901 超音波クリーニング用、電源電圧範囲の広いシングル・チャネル PWM 入力ピエゾ・トランスデューサ・ドライバ

1 特長

- 広い動作電源電圧範囲 (12V~48V)
- 最大 50W のピーク電力をサポート
- 90mΩ の出力 MOSFET による高効率の出力段
- パワーオン・リセットにより、電源シーケンシングなしで電源立ち上げ時の保護を実現
- 以下の自己保護回路を内蔵
 - 低電圧保護
 - 過熱保護
 - 過負荷保護
 - 短絡保護
- 44 ピン HTSSOP パッケージ (DDV) で供給

2 アプリケーション

- サーマル・イメージング・カメラ
- 交通監視カメラ
- マシン・ビジョン・カメラ
- ワイヤレス・セキュリティ・カメラ
- ドローン・ビジョン

3 概要

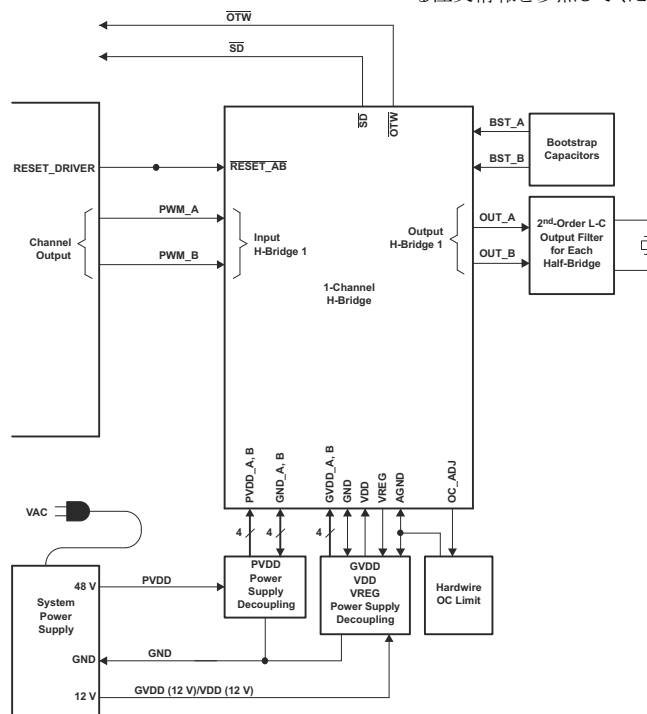
DRV2901 は高性能レンズ・クリーナ・トランスデューサ・ドライバです。このシステムで必要とされるのは、シンプルな受動 LC 復調フィルタだけであり、実績のある EMI 規格に準拠した、高品質かつ高効率の増幅を実現します。このデバイスには、2 系統の電源 (1 系統は GVDD および VDD 用の 12 V、もう 1 系統は PVDD 用の 12V~48 V) が必要です。DRV2901 は、パワーオン・リセットを内蔵しており、電源オン・シーケンスを必要としません。

DRV2901 のチップ上には革新的な保護システムが搭載されており、システムに損傷を与える可能性のあるさまざまな故障状態からデバイスを保護します。これらの保護機能には、短絡保護、過電流保護、低電圧保護、および過熱に対する保護があります。DRV2901 には独自に新設計された電流制限回路が備わっており、高レベルの過渡状態において、デバイスがシャットダウンする可能性を低減します。

製品情報 (1)

部品番号	パッケージ	本体サイズ (公称)
DRV2901	44 ピン HTSSOP	14.0mm×6.1mm

(1) 利用可能なパッケージについては、このデータシートの末尾にある注文情報を参照してください。



DRV2901 機能ブロック図



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

DATE	REVISION	NOTES
January 2023	*	Initial release.

5 Pin Configuration and Functions

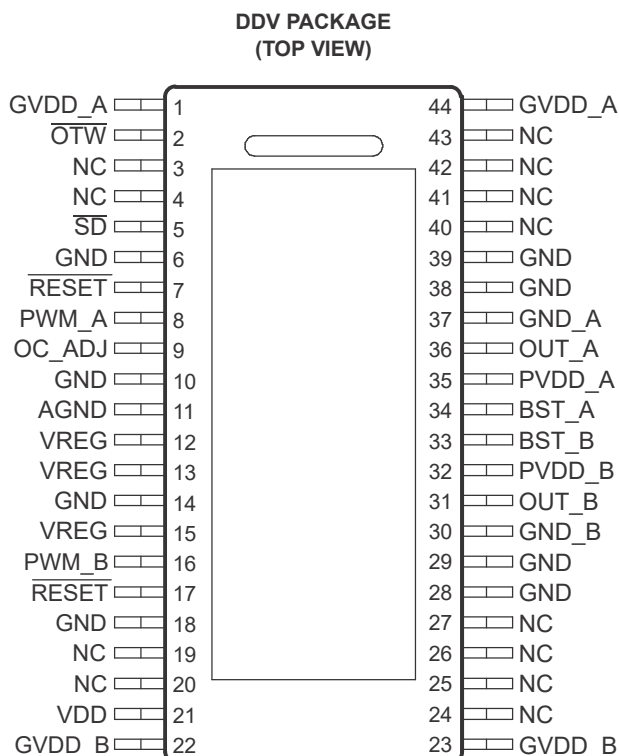


图 5-1. DDV Package 44-Pin HTSSOP PowerPad Top View

表 5-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
AGND	11	P	Analog ground
BST_A	34	P	HS bootstrap supply (BST), external .033-μF capacitor to OUT_A required
BST_B	33	P	HS bootstrap supply (BST), external .033-μF capacitor to OUT_B required
GND	6, 10, 14, 18, 28, 29, 38, 39	P	Ground.
GND_A	37	P	Power ground for half-bridge A
GND_B	30	P	Power ground for half-bridge B
GVDD_A	1, 44	P	Gate-drive voltage supply requires 0.1-μF capacitor to AGND
GVDD_B	22, 23	P	Gate-drive voltage supply requires 0.1-μF capacitor to AGND
NC	3, 4, 19, 20, 24, 25, 26, 27, 40, 41, 42, 43	—	Do not connect.
OC_ADJ	9	O	Analog overcurrent programming pin requires resistor to ground
OTW	2	O	Overtemperature warning signal, open-drain, active-low
OUT_A	36	O	Output, half-bridge A
OUT_B	31	O	Output, half-bridge B
PVDD_A	35	P	Power supply input for half-bridge A requires close decoupling of 0.01-μF capacitor in parallel with a 1.0-μF capacitor to GND_A.
PVDD_B	32	P	Power supply input for half-bridge B requires close decoupling of 0.01-μF capacitor in parallel with a 1.0-μF capacitor to GND_B.
PWM_A	8	I	Input signal for half-bridge A

表 5-1. Pin Functions (continued)

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
PWM_B	16	I	Input signal for half-bridge B
RESET	7, 17	I	Reset signal for half-bridge A and B, active-low
$\overline{\text{SD}}$	5	O	Shutdown signal, open-drain, active-low
VDD	21	P	Power supply for digital voltage regulator requires a 47- μF capacitor in parallel with a 0.1- μF capacitor to GND for decoupling.
VREG	12, 13, 15	P	Digital regulator supply filter pin requires 0.1- μF capacitor to AGND.

(1) I = input, O = output, P = power

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range unless otherwise noted ⁽¹⁾

VDD to AGND	–0.3 V to 13.2 V
GVDD_X to AGND	–0.3 V to 13.2 V
PVDD_X to GND_X ⁽²⁾	–0.3 V to 71 V
OUT_X to GND_X ⁽²⁾	–0.3 V to 71V
BST_X to GND_X ⁽²⁾	–0.3 V to 79.7 V
VREG to AGND	–0.3 V to 4.2 V
GND_X to GND	–0.3 V to 0.3 V
GND_X to AGND	–0.3 V to 0.3 V
GND to AGND	–0.3 V to 0.3 V
PWM_X, OC_ADJ, M1, M2, M3 to AGND	–0.3 V to 4.2 V
RESET_X, $\overline{SD}$, $\overline{OTW}$ to AGND	–0.3 V to 7 V
Maximum continuous sink current ($\overline{SD}$, $\overline{OTW}$)	9 mA
Maximum operating junction temperature range, T _J	0°C to 125°C
Storage temperature	–40°C to 125°C
Lead temperature, 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Minimum pulse duration, low	50 ns

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) These voltages represent the dc voltage + peak ac waveform measured at the terminal of the device in all conditions.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾	V
		Charged-device model (CDM), per AEC Q100-011	

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

			MIN	TYP	MAX	UNIT
PVDD_X	Half-bridge supply	DC supply voltage	0	50	52.5	V
GVDD_X	Supply for logic regulators and gate-drive circuitry	DC supply voltage	10.8	12	13.2	V
VDD	Digital regulator input	DC supply voltage	10.8	12	13.2	V
L _{Output}	Output-filter inductance	Minimum output inductance under short-circuit condition	5	10		μH
F _{PWM}	PWM frame rate		192	384	432	kHz
T _J	Junction temperature		0		125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		DRV2901	UNIT
		DDV 44-PINS HTSSOP	
		JEDEC STANDARD 4 LAYER PCB	
R _{θJA}	Junction-to-ambient thermal resistance	50.7	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	0.36	°C/W

THERMAL METRIC ⁽¹⁾		DRV2901	UNIT
		DDV 44-PINS HTSSOP	
		JEDEC STANDARD 4 LAYER PCB	
$R_{\theta JB}$	Junction-to-board thermal resistance	24.4	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.19	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	24.2	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	n/a	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

$R_L = 6\ \Omega$, $F_{PWM} = 384\text{ kHz}$, unless otherwise noted. All performance is in accordance with recommended operating conditions unless otherwise specified.

PARAMETER		TEST CONDITIONS	DRV2900			UNIT
			MIN	TYP	MAX	
Internal Voltage Regulator and Current Consumption						
VREG	Voltage regulator, only used as a reference node	VDD = 12 V	2.95	3.3	3.65	V
IVDD	VDD supply current	Operating, 50% duty cycle	10			mA
		Idle, reset mode	6			
IGVDD_X	Gate supply current per half-bridge	50% duty cycle	8			mA
		Reset mode	0.3			
IPVDD_X	Half-bridge idle current	50% duty cycle, without output filter or load	15			mA
		Reset mode, no switching	500			
Output Stage MOSFETs						
R _{DSon,LS}	Drain-to-source resistance, LS	T _J = 25°C, includes metallization resistance, GVDD = 12 V	90			mΩ
R _{DSon,HS}	Drain-to-source resistance, HS	T _J = 25°C, includes metallization resistance, GVDD = 12 V	90			mΩ
I/O Protection						
V _{uvp,G}	Undervoltage protection limit, GVDD_X		8.5			V
V _{uvp,hyst} ⁽¹⁾			400			mV
OTW ⁽¹⁾	Overtemperature warning		115	125	135	°C
OTW _{HYST} ⁽¹⁾	Temperature drop needed below OTW temp. for OTW to be inactive after the OTW event		25			°C
OTE ⁽¹⁾	Overtemperature error		145	155	165	°C
OTE-OTW _{differential} ⁽¹⁾	OTE-OTW differential		25			°C
OTE _{HYST} ⁽¹⁾	A reset needs to occur for $\overline{SD}$ for be released following an OTE event.		25			°C
OLPC	Overload protection counter	F _{PWM} = 384 kHz	1.3			ms
I _{OC}	Overcurrent limit protection	Resistor—programmable, nominal, R _{OCP} = 22 kΩ	12			A
I _{OCT}	Overcurrent response time	Time from application of short condition to Hi-Z of affected 1/2 bridge	250			ns
R _{OCP}	OC programming resistor range	Resistor tolerance = 5%	22	69		kΩ
R _{PD}	Internal pulldown resistor at the output of each half-bridge	Connected when RESET is active to provide bootstrap capacitor charge. Not used in SE mode	1.0			kΩ

$R_L = 6\ \Omega$, $F_{PWM} = 384\ \text{kHz}$, unless otherwise noted. All performance is in accordance with recommended operating conditions unless otherwise specified.

PARAMETER		TEST CONDITIONS	DRV2900			UNIT
			MIN	TYP	MAX	
Static Digital Specifications						
V _{IH}	High-level input voltage	PWM_A, PWM_B, RESET_AB	2			V
V _{IL}	Low-level input voltage		0.8			V
Leakage	Input leakage current		-100 100			μA
OTW/SHUTDOWN (SD)						
R _{INT_PU}	Internal pullup resistance, OTW to VREG, SD to VREG		20	26	35	kΩ
V _{OH}	High-level output voltage	Internal pullup resistor	2.95	3.3	3.65	V
		External pullup of 4.7 kΩ to 5 V	4.5 5			
V _{OL}	Low-level output voltage	I _O = 4 mA	0.2 0.4			V
FANOUT	Device fanout OTW, SD	No external pullup	30			Devices

(1) Specified by design

6.6 Typical Characteristics

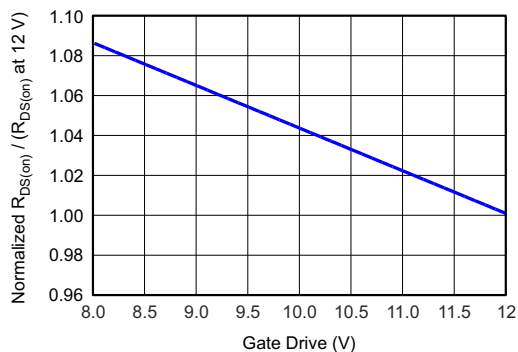


FIG 6-1. Normalized $R_{DS(on)}$ vs Gate Drive

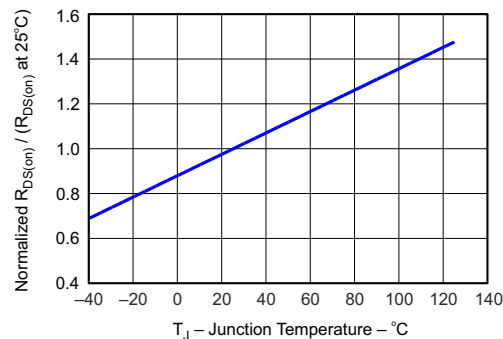


FIG 6-2. Normalized $R_{DS(on)}$ vs Junction Temperature

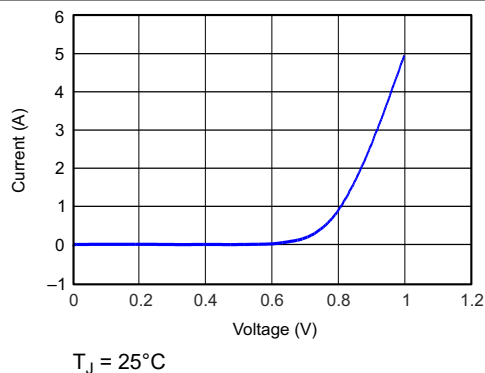


FIG 6-3. Drain To Source Diode Forward On Characteristics

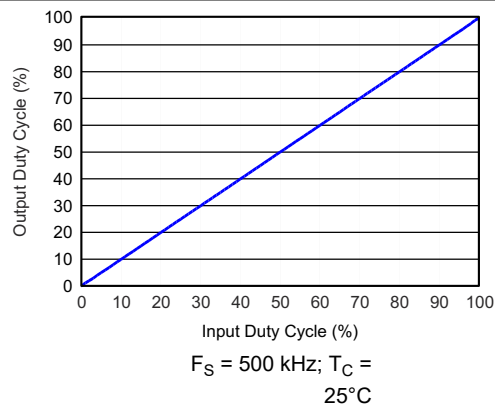


FIG 6-4. Output Duty Cycle vs Input Duty Cycle

7 Detailed Description

7.1 Block Diagrams

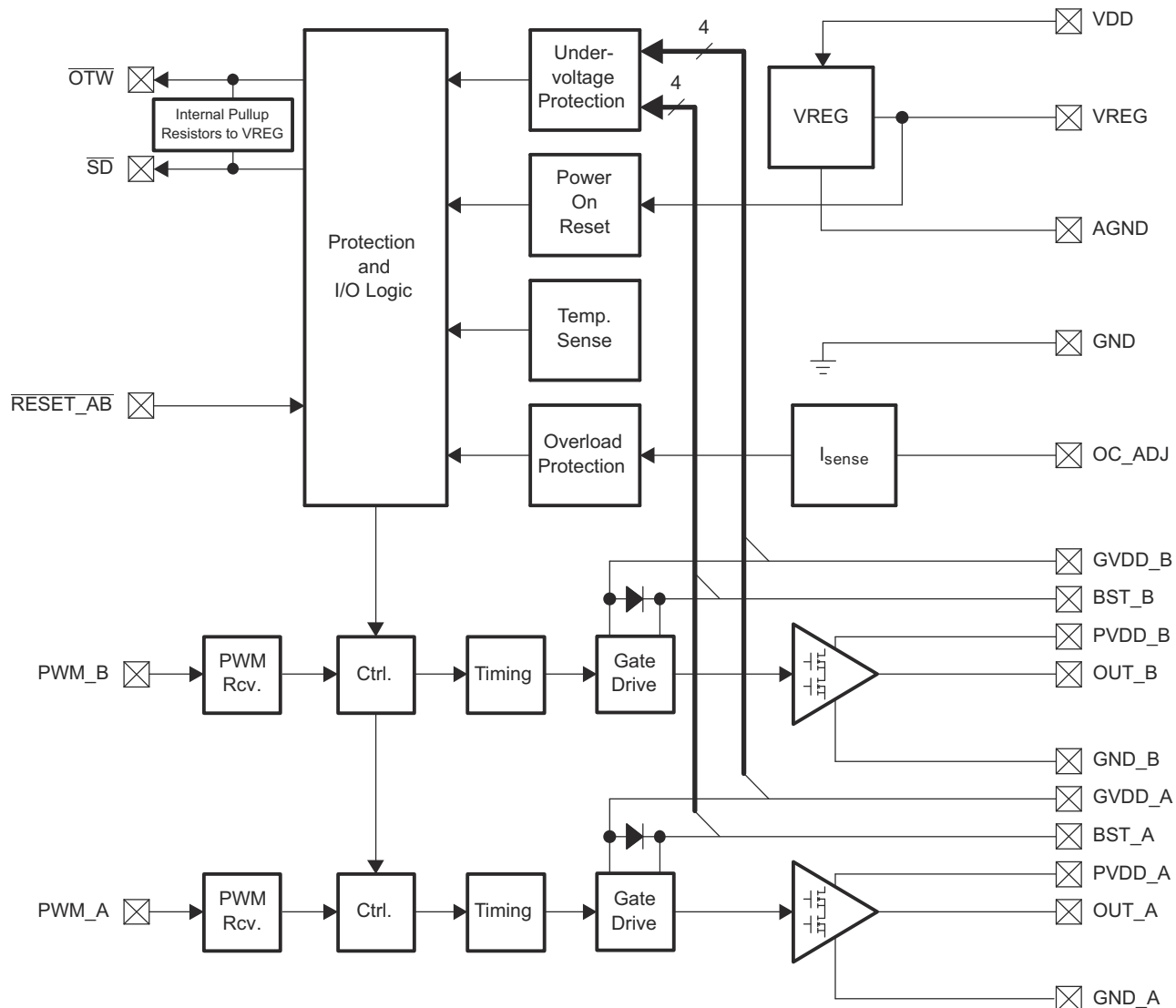
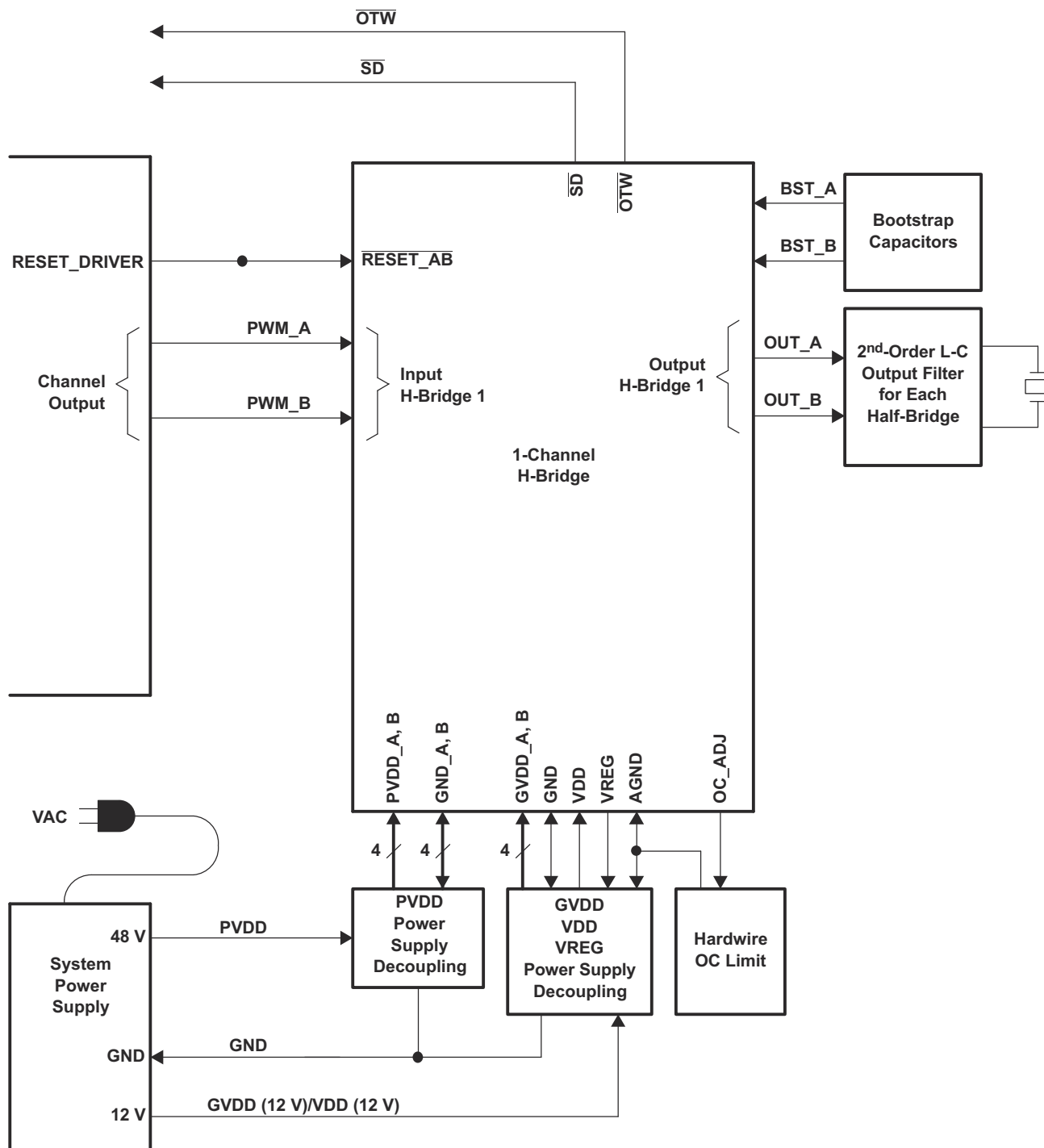


图 7-1. System Block Diagram



7-2. Functional Block Diagram

7.2 Feature Description

7.2.1 Error Reporting

The $\overline{SD}$ and $\overline{OTW}$ pins are both active-low, open-drain outputs. Their function is for protection-mode signaling to a PWM controller or other system-control device.

Any fault resulting in device shutdown, such as overtemperature shut down, overcurrent shut-down, or undervoltage protection, is signaled by the $\overline{SD}$ pin going low. Likewise, $\overline{OTW}$ goes low when the device junction temperature exceeds 125°C (see Table 7-1).

表 7-1. Protection Mode Signal Descriptions

SD	OTW	DESCRIPTION
0	0	Overtemperature warning and (overtemperature shut down or overcurrent shut down or undervoltage protection) occurred
0	1	Overcurrent shut-down or GVDD undervoltage protection occurred
1	0	Overtemperature warning
1	1	Device under normal operation

TI recommends monitoring the $\overline{\text{OTW}}$ signal using the system microcontroller and responding to an $\overline{\text{OTW}}$ signal by reducing the load current to prevent further heating of the device resulting in device overtemperature shutdown (OTSD).

To reduce external component count, an internal pullup resistor to internal VREG (3.3 V) is provided on both $\overline{\text{SD}}$ and $\overline{\text{OTW}}$ outputs. Level compliance for 5-V logic can be obtained by adding external pullup resistors to 5 V (see the *Electrical Characteristics* section of this data sheet for further specifications).

7.2.2 Device Reset

Reset pin is provided for control of the H-bridge. When $\overline{\text{RESET_AB}}$ is asserted low, the power-stage FETs in H-bridge are forced into a high-impedance (Hi-Z) state.

A rising-edge transition on reset input allows the device to resume operation after a shut-down fault and clears the fault and $\overline{\text{SD}}$ pin.

7.2.3 Device Protection System

7.2.3.1 Overcurrent (OC) Protection With Current Limiting and Overload Detection

The device has independent, fast-reacting current detectors with programmable trip threshold (OC threshold) on all high-side and low-side power-stage FETs. See the following table for OC-adjust resistor values. The detector outputs are closely monitored by two protection systems. The first protection system controls the power stage in order to prevent the output current from further increasing, i.e., it performs a current-limiting function rather than prematurely shutting down during combinations of high-level transients and extreme load impedance drops. If the high-current situation persists, i.e., the power stage is being overloaded, a second protection system triggers a latching shutdown, resulting in the power stage being set in the high-impedance (Hi-Z) state. Current limiting and overload protection are independent for half-bridges A and B

- For the lowest-cost bill of materials in terms of component selection, the OC threshold measure should be limited, considering the power output requirement and minimum load impedance. Higher-impedance loads require a lower OC threshold.
- The demodulation-filter inductor must retain at least 5 μH of inductance at twice the OC threshold setting.

Unfortunately, most inductors have decreasing inductance with increasing temperature and increasing current (saturation). To some degree, an increase in temperature naturally occurs when operating at high output currents, due to core losses and the dc resistance of the inductor's copper winding. A thorough analysis of inductor saturation and thermal properties is strongly recommended.

Setting the OC threshold too low might cause issues such as lack of enough output power and/or unexpected shutdowns due to too-sensitive overload detection.

For added flexibility, the OC threshold is programmable within a limited range using a single external resistor connected between the OC_ADJ pin and AGND. (See the *Electrical Characteristics* section of this data sheet for information on the correlation between programming-resistor value and the OC threshold.) It should be noted that a properly functioning overcurrent detector assumes the presence of a properly designed demodulation filter at the power-stage output. Short-circuit protection is not provided directly at the output pins of the power stage but only on the transducer terminals (after the demodulation filter). It is required to follow certain guidelines when selecting the OC threshold and an appropriate demodulation inductor:

OC-Adjust Resistor Values (k Ω)	Max. Current Before OC Occurs (A)
22	12.2

OC-Adjust Resistor Values (k Ω)	Max. Current Before OC Occurs (A)
27	10.5
47	6.4
68	4.0
100	3.0

7.2.3.2 Overtemperature Protection

The DRV2901 has a two-level temperature-protection system that asserts an active-low warning signal ($\overline{OTW}$) when the device junction temperature exceeds 125°C (nominal) and, if the device junction temperature exceeds 155°C (nominal), the device is put into thermal shutdown, resulting in all half-bridge outputs being set in the high-impedance (Hi-Z) state and $\overline{SD}$ being asserted low. OTE is latched in this case and $\overline{RESET_AB}$ must be asserted low.

7.2.3.3 Undervoltage Protection (UVP) and Power-On Reset (POR)

The UVP and POR circuits of the DRV2901 fully protect the device in any power-up/down and brownout situation. While powering up, the POR circuit resets the overload circuit (OLP) and ensures that all circuits are fully operational when the GVDD_X and VDD supply voltages reach 9.8 V (typical). Although GVDD_X and VDD are independently monitored, a supply voltage drop below the UVP threshold on any VDD or GVDD_X pin results in all half-bridge outputs immediately being set in the high-impedance (Hi-Z) state and $\overline{SD}$ being asserted low. The device automatically resumes operation when all supply voltage on the bootstrap capacitors have increased above the UVP threshold.

8 Applications and Implementation

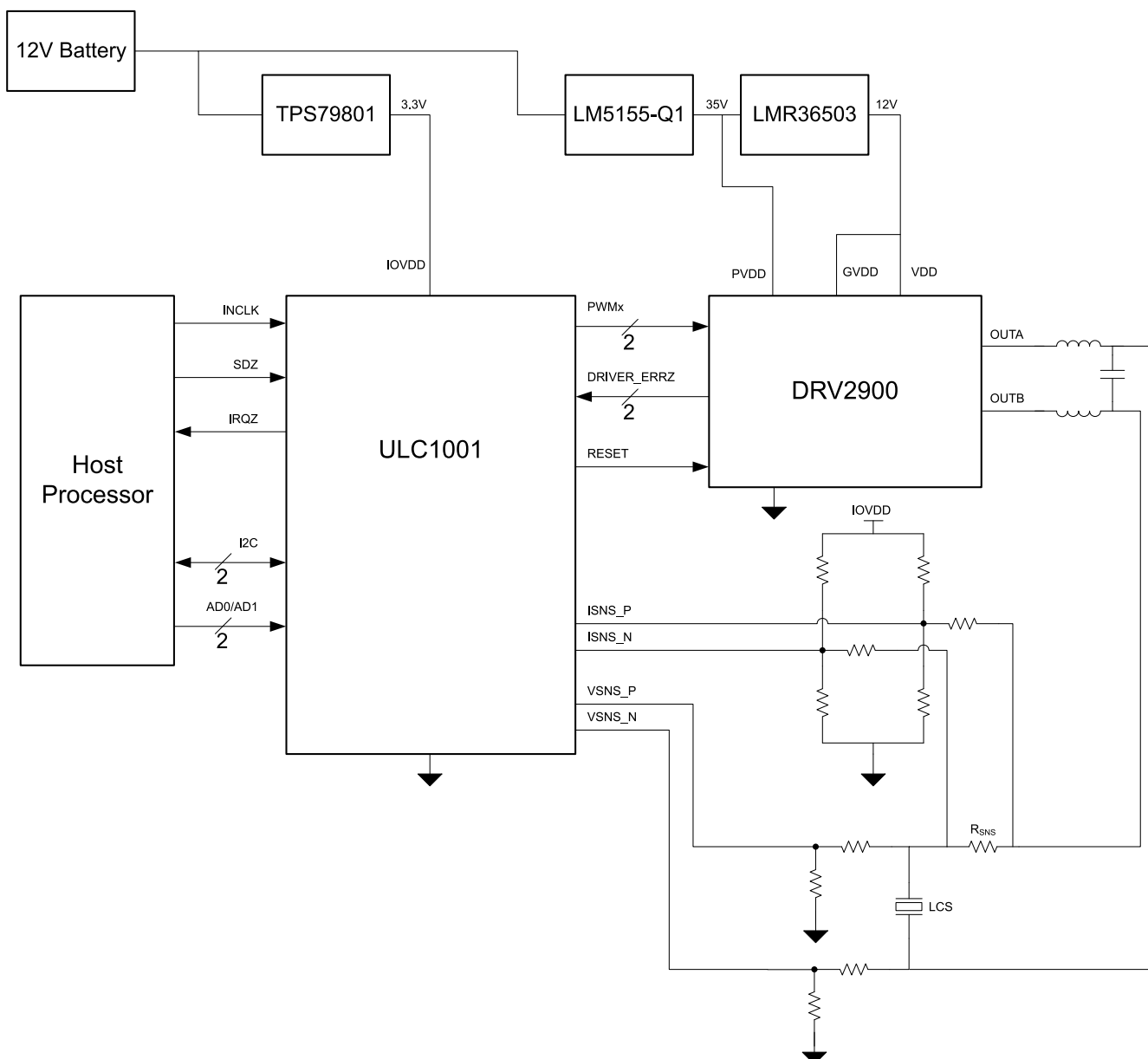
注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The DRV2901 is a high performance lens cleaner transducer driver. This device requires two power supplies, at 12 V for GVDD and VDD, and 12 V to 48 V for PVDD. The DRV2901 does not require power-up sequencing due to internal power-on reset.

8.2 Typical Application



8-1. Typical System Diagram

9 Power Supply Recommendations

9.1 System Power-up/power-down Sequence

9.1.1 Powering Up

The DRV2901 does not require a power-up sequence. The outputs of the H-bridges remain in a high impedance state until the gate-drive supply voltage (GVDD_X) and VDD voltage are above the undervoltage protection (UVP) voltage threshold (see the *Electrical Characteristics* section of this data sheet). Although not specifically required, it is recommended to hold $\overline{\text{RESET_AB}}$ in a low state while powering up the device. This allows an internal circuit to charge the external bootstrap capacitors by enabling a weak pulldown of the half-bridge output.

9.1.2 Powering Down

The DRV2901 does not require a power-down sequence. The device remains fully operational as long as the gate-drive supply (GVDD_X) voltage and VDD voltage are above the undervoltage protection (UVP) voltage threshold (see the *Electrical Characteristics* section of this data sheet). Although not specifically required, it is a good practice to hold $\overline{\text{RESET_AB}}$ low during power down, thus preventing any artifacts.

9.2 System Design Recommendations

9.2.1 VDD Pin

The transient current in VDD pin could be significantly higher than average current through VDD pin. A low resistive path to GVDD should be used. A 22- μF to 47- μF capacitor should be placed on VDD pin beside the 100-nF to 1- μF decoupling capacitor to provide a constant voltage during transient.

9.2.2 VREG Pin

The VREG pin is used for internal logic and should not be used as a voltage source for external circuitry. The capacitor on VREG pin should be connected to AGND.

9.2.3 OTW Pin

$\overline{\text{OTW}}$ reporting indicates the device approaching high junction temperature. This signal can be used with MCU to decrease system power when $\overline{\text{OTW}}$ is low in order to prevent OT shut down at a higher temperature.

No external pull up resistor or 3.3 V power supply is needed for 3.3 V logic. The $\overline{\text{OTW}}$ pin has an internal pullup resistor connecting to an internal 3.3 V to reduce external component count. For 5 V logic, an external pull up resistor to 5 V is needed.

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DRV2901DDVR	Active	Production	HTSSOP (DDV) 44	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	0 to 125	DRV2901
DRV2901DDVR.A	Active	Production	HTSSOP (DDV) 44	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	0 to 125	DRV2901

- ⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).
- ⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- ⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- ⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- ⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- ⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

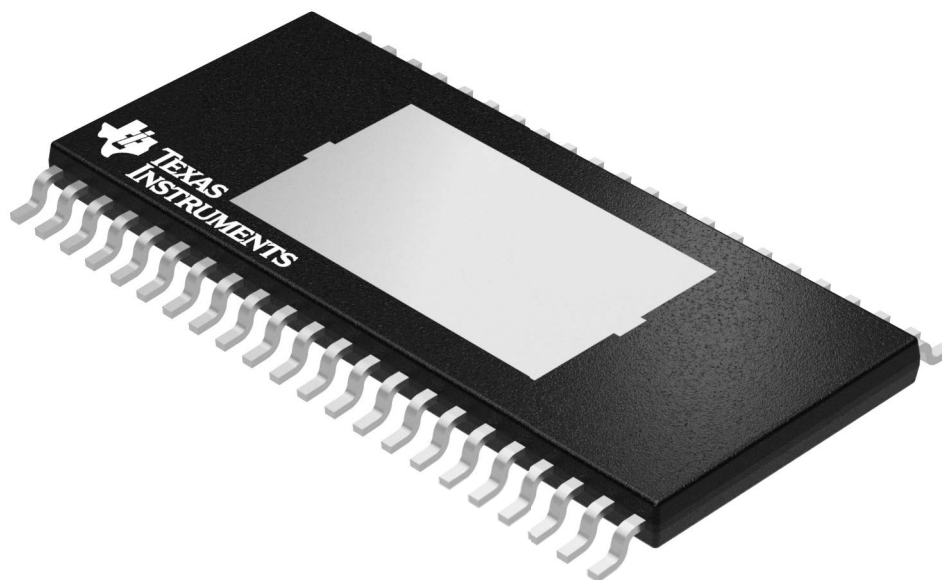
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DRV2901DDVR	HTSSOP	DDV	44	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

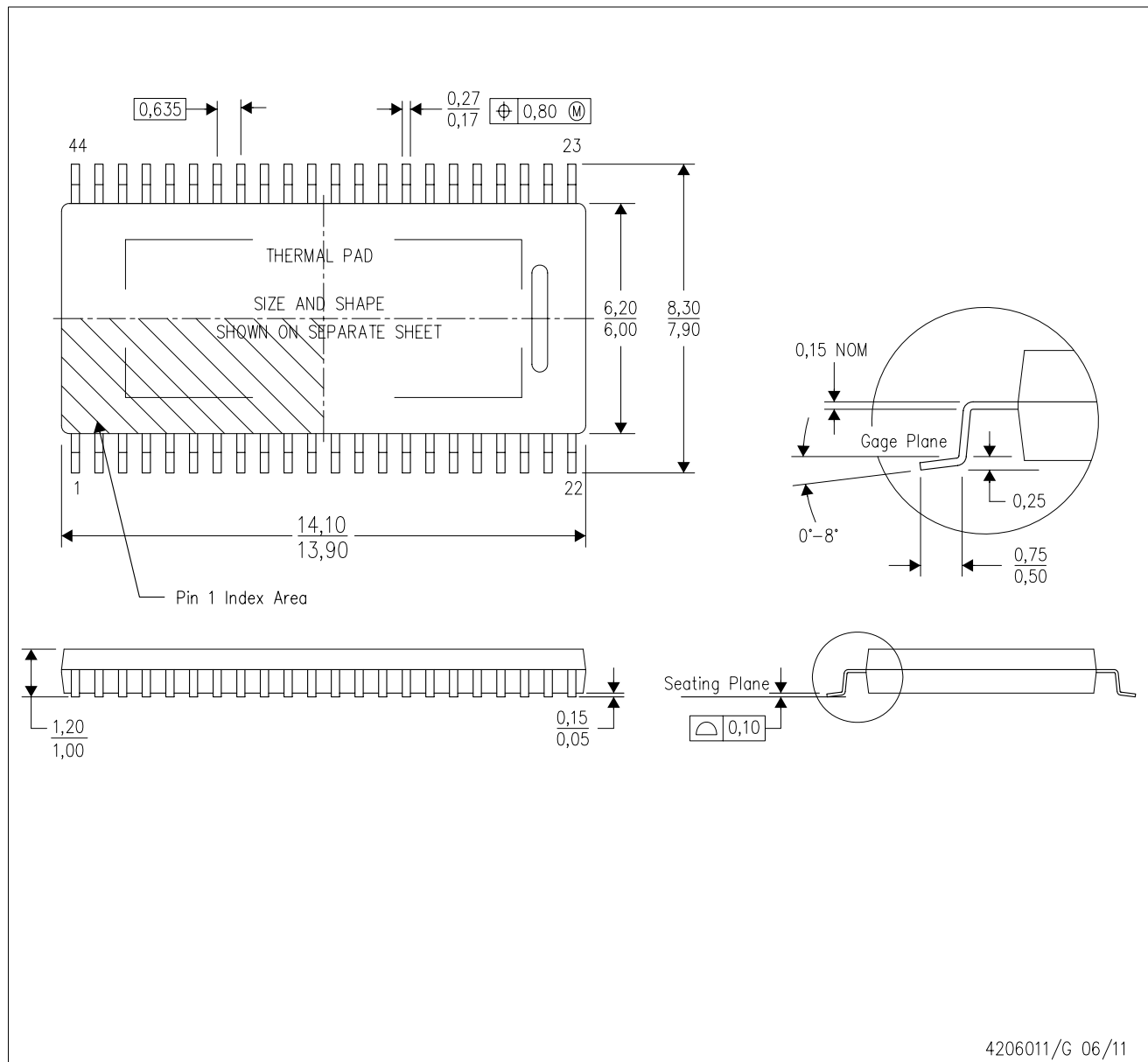
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DRV2901DDVR	HTSSOP	DDV	44	2000	350.0	350.0	43.0



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

MECHANICAL DATA

DDV (R-PDSO-G44) PowerPAD™ PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - This package is designed to be attached directly to an external heatsink. Refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>. See the product data sheet for details regarding the exposed thermal pad dimensions.

PowerPAD is a trademark of Texas Instruments.

DDV (R-PDSO-G44)

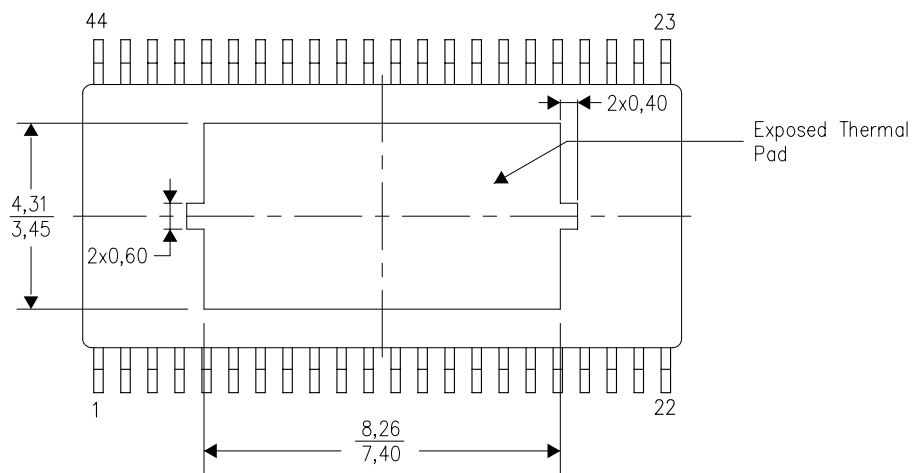
PowerPAD™ SMALL OUTLINE PACKAGE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

Exposed Thermal Pad Dimensions

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NOTE: All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

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